

KW CELMM1.TG

OSLON® Boost HM

OSLON Boost HM utilizes the high current capability of the latest chip generation in a special package for good thermal behaviour. The LED is characterized by a high luminance of up to 255 cd / mm² and a high luminous flux. Therefore this LED is ideally suited as a powerful light source for ultra-slim headlamp designs.



Applications

- Headlamps, LED & Laser & Night Vision

Features:

- Package: Ceramic package
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: Cx = 0.32, Cy = 0.33 acc. to CIE 1931 (● white)
- Corrosion Robustness Class: 3A
- Qualifications: AEC-Q102 Qualified with RV-level 1
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)

Ordering Information

Type	Luminous Flux ¹⁾ $I_F = 1500 \text{ mA}$ Φ_V	Ordering Code
KW CELMM1.TG-S3SA-ebvFfcbB46-8F8H	375 ... 560 lm	Q65112A9875

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature ²⁾	T_{op}	min.	-40 °C
		max.	135 °C
Storage Temperature	T_{stg}	min.	-40 °C
		max.	135 °C
Junction Temperature	T_j	max.	150 °C
Junction Temperature for short time applications*	T_j	max.	175 °C
Forward Current $T_s = 25\text{ °C}$	I_F	min.	50 mA
		max.	1650 mA
Forward Current pulsed $D = 0.005$; $T_s = 25\text{ °C}$	$I_{F\ pulse}$	max.	2000 mA
Surge Current $t \leq 10\ \mu s$; $D = 0.005$; $T_s = 25\text{ °C}$	I_{FS}	max.	2500 mA
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	V_{ESD}		8 kV
Reverse current ³⁾	I_R	max.	200 mA

* The median lifetime (L70/B50) for $T_j = 175\text{ °C}$ is 100h.

Characteristics

$I_F = 1500 \text{ mA}$; $T_S = 25 \text{ °C}$

Parameter	Symbol		Values
Chromaticity Coordinate ⁴⁾	Cx	typ.	0.32
	Cy	typ.	0.33
Viewing angle at 50% I_V	2ϕ	typ.	120 °
Forward Voltage ⁵⁾ $I_F = 1500 \text{ mA}$	V_F	min.	3.00 V
		typ.	3.41 V
		max.	3.75 V
Reverse voltage (ESD device)	$V_{R\text{ESD}}$	min.	45 V
Reverse voltage ³⁾ $I_R = 20 \text{ mA}$	V_R	max.	1.2 V
Real thermal resistance junction/solderpoint ⁶⁾	$R_{\text{thJS real}}$	typ.	6.7 K / W
		max.	8.1 K / W
Electrical thermal resistance junction/solderpoint ⁶⁾ with efficiency $\eta_e = 22 \%$	$R_{\text{thJS elec.}}$	typ.	5.2 K / W
		max.	6.3 K / W

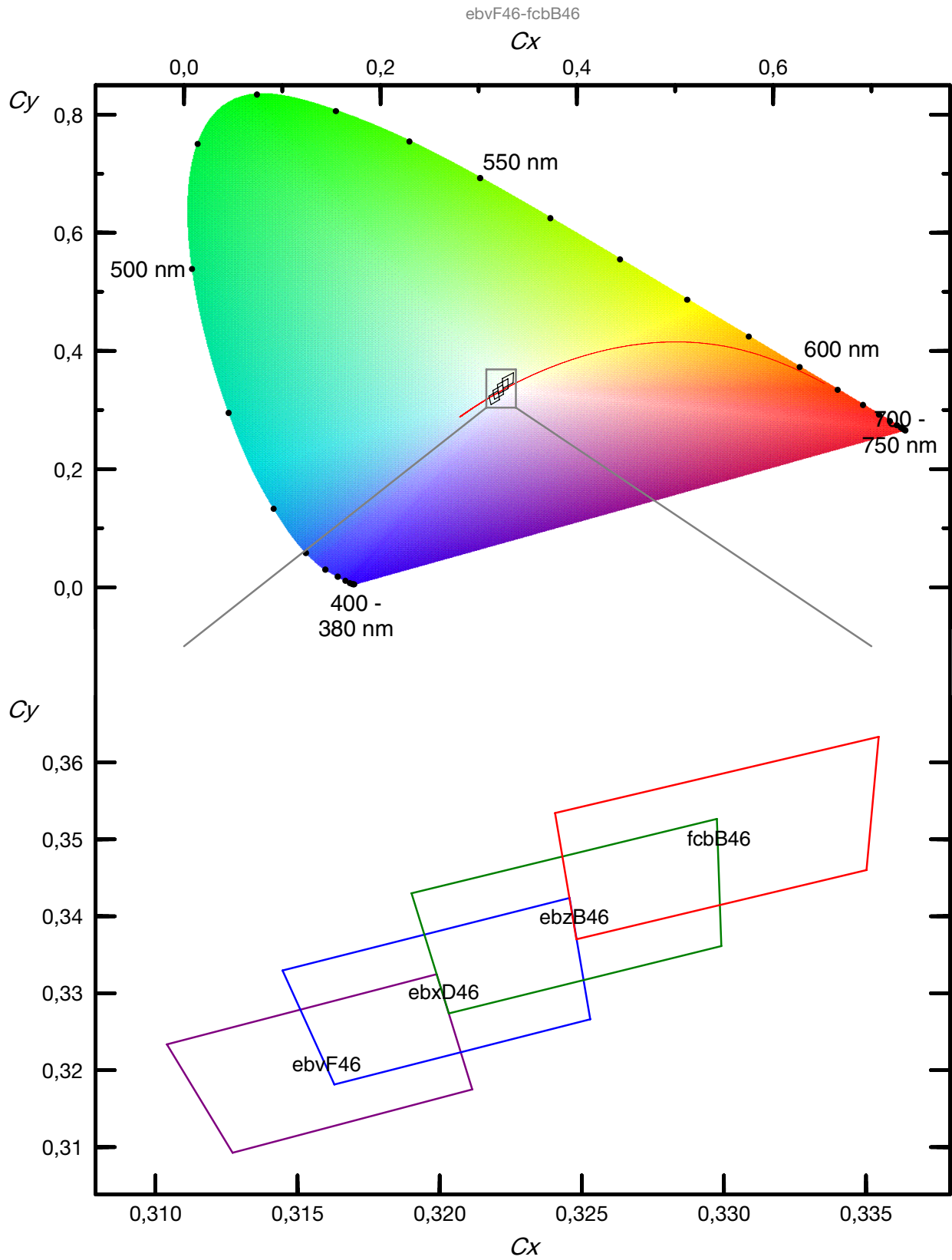
Brightness Groups

Group	Luminous Flux ¹⁾ $I_F = 1500 \text{ mA}$ min. Φ_V	Luminous Flux ¹⁾ $I_F = 1500 \text{ mA}$ max. Φ_V
S3	375 lm	395 lm
S4	395 lm	415 lm
S5	415 lm	435 lm
S6	435 lm	460 lm
S7	460 lm	485 lm
S8	485 lm	510 lm
S9	510 lm	535 lm
SA	535 lm	560 lm

Forward Voltage Groups

Group	Forward Voltage ⁵⁾ $I_F = 1500 \text{ mA}$ min. V_F	Forward Voltage ⁵⁾ $I_F = 1500 \text{ mA}$ max. V_F
8F	3.00 V	3.25 V
8G	3.25 V	3.50 V
8H	3.50 V	3.75 V

Chromaticity Coordinate Groups



Chromaticity Coordinate Groups ⁴⁾

Group	Cx	Cy	Group	Cx	Cy
ebvF46	0.3127	0.3093	ebzB46	0.3203	0.3274
	0.3212	0.3175		0.3299	0.3361
	0.3199	0.3325		0.3298	0.3526
	0.3104	0.3234		0.3190	0.3430
ebxD46	0.3163	0.3181	fcbB46	0.3248	0.3370
	0.3253	0.3266		0.3350	0.3460
	0.3246	0.3424		0.3355	0.3633
	0.3145	0.3330		0.3241	0.3534

Group Name on Label

Example: S3-ebvF46-8F

Brightness

Color Chromaticity

Forward Voltage

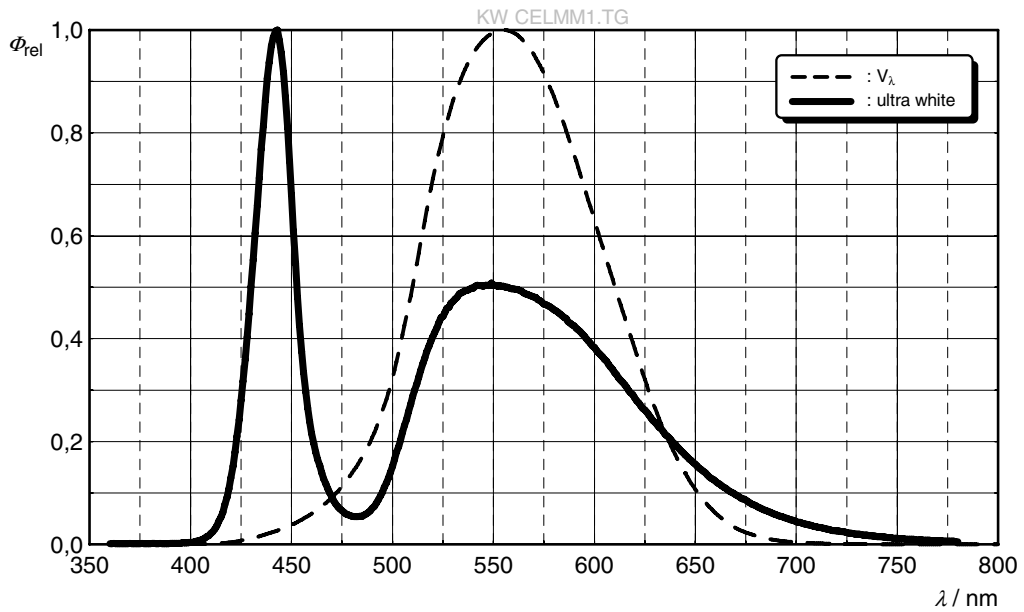
S3

ebvF46

8F

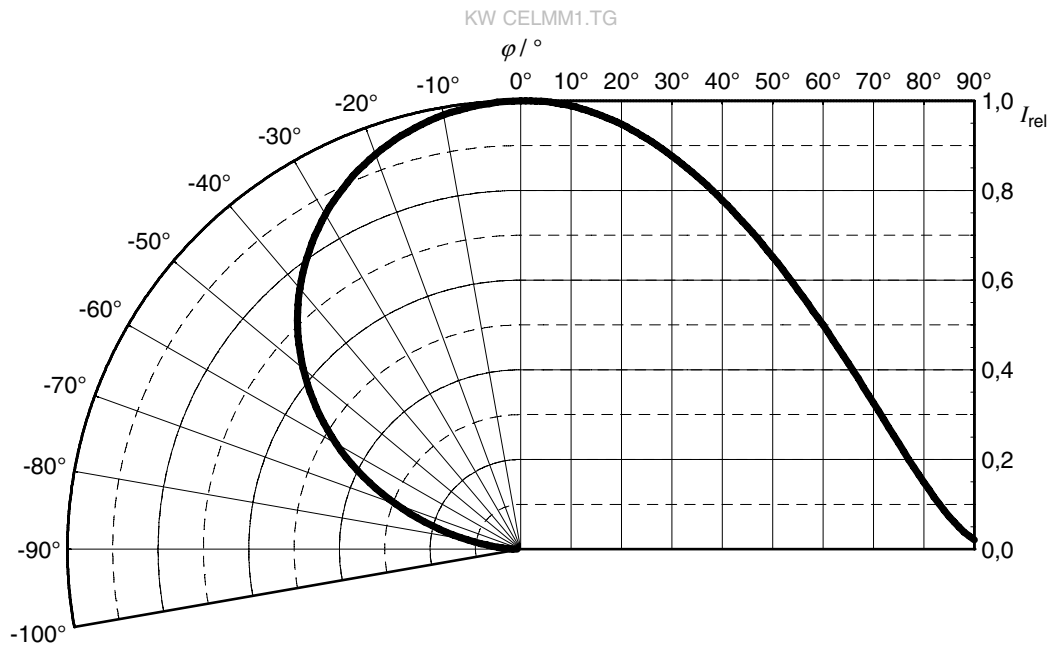
Relative Spectral Emission ⁷⁾

$\Phi_{rel} = f(\lambda)$; $I_F = 1500 \text{ mA}$; $T_J = 25 \text{ }^\circ\text{C}$



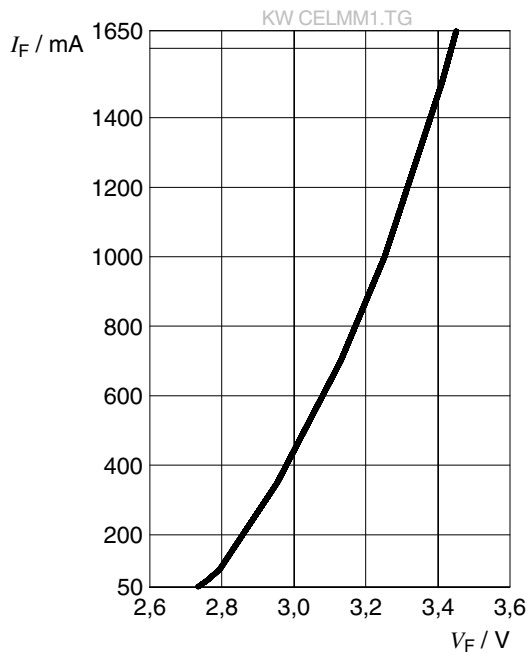
Radiation Characteristics ⁷⁾

$I_{rel} = f(\phi)$; $T_J = 25 \text{ }^\circ\text{C}$



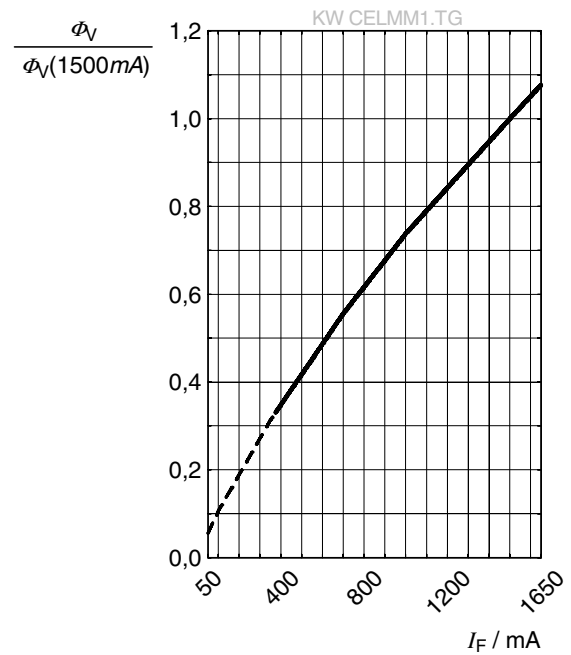
Forward current ⁷⁾

$$I_F = f(V_F); T_J = 25 \text{ }^\circ\text{C}$$



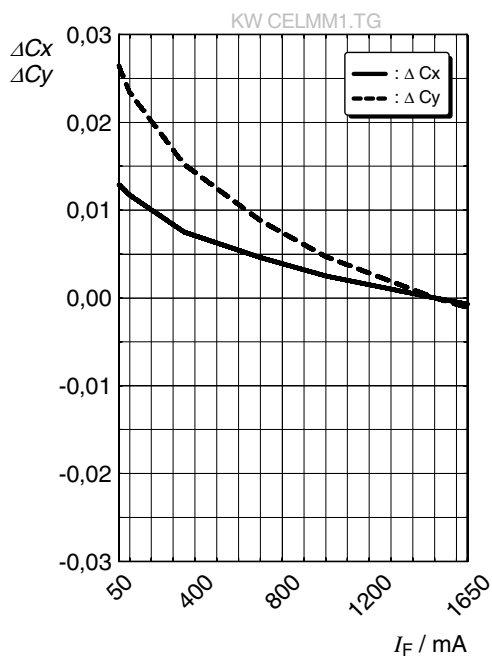
Relative Luminous Flux ^{7), 8)}

$$\Phi_V / \Phi_V(1500 \text{ mA}) = f(I_F); T_J = 25 \text{ }^\circ\text{C}$$



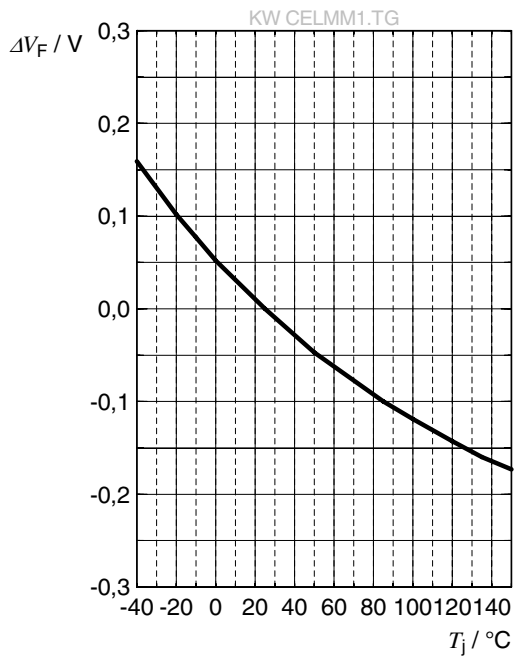
Chromaticity Coordinate Shift ⁷⁾

$$\Delta C_x, \Delta C_y = f(I_F); T_J = 25 \text{ }^\circ\text{C}$$



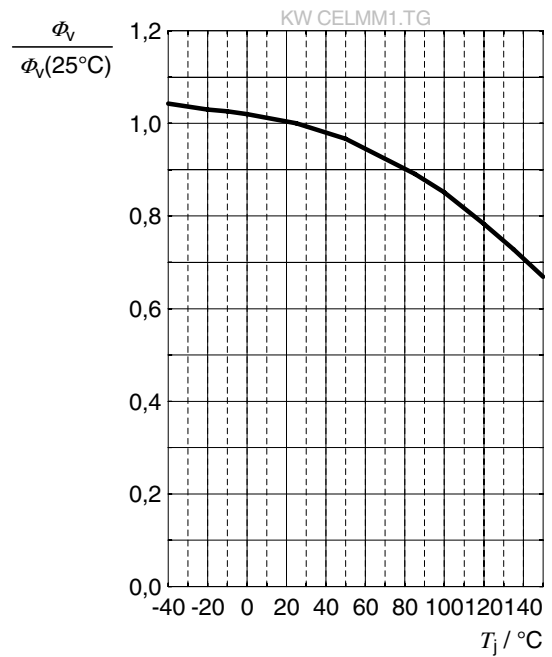
Forward Voltage ⁷⁾

$$\Delta V_F = V_F - V_F(25\text{ }^\circ\text{C}) = f(T_j); I_F = 1500\text{ mA}$$



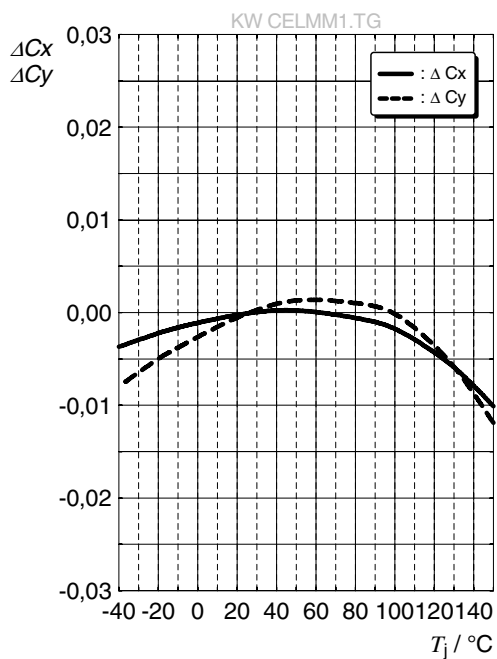
Relative Luminous Flux ⁷⁾

$$\Phi_V / \Phi_V(25\text{ }^\circ\text{C}) = f(T_j); I_F = 1500\text{ mA}$$



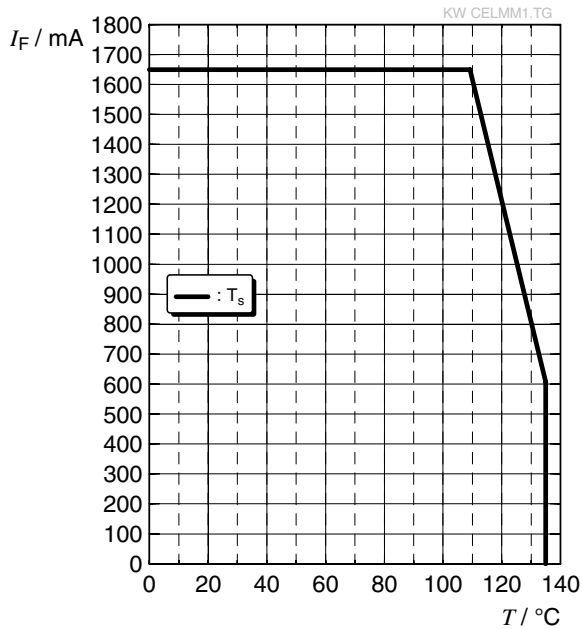
Chromaticity Coordinate Shift ⁷⁾

$$\Delta C_x, \Delta C_y = f(T_j); I_F = 1500\text{ mA}$$



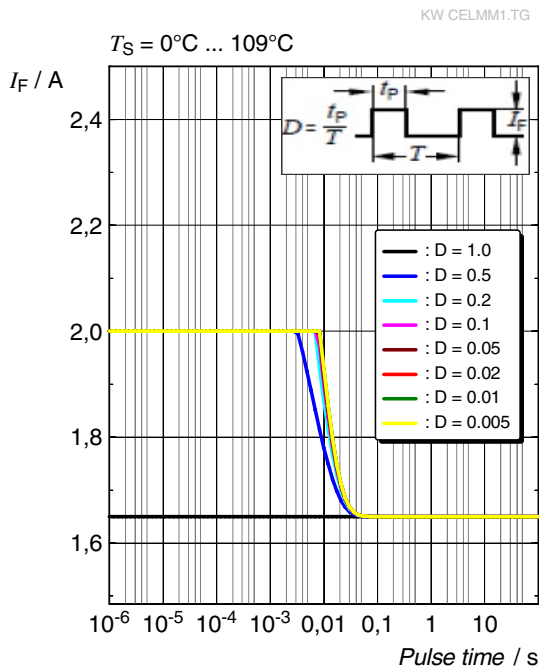
Max. Permissible Forward Current

$$I_F = f(T)$$



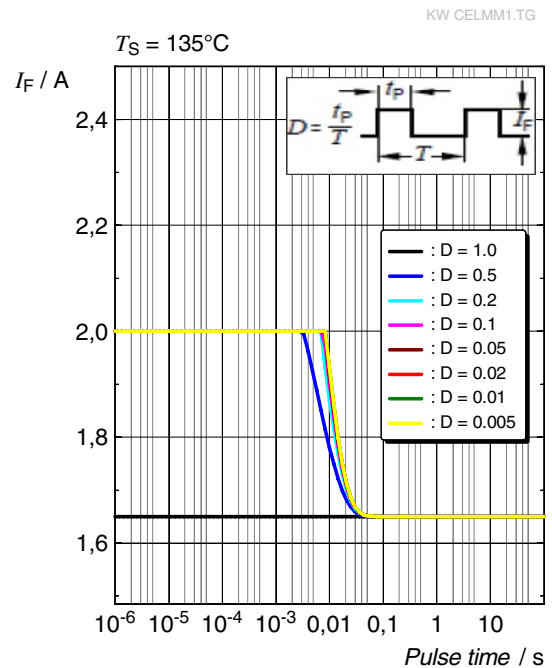
Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}$$



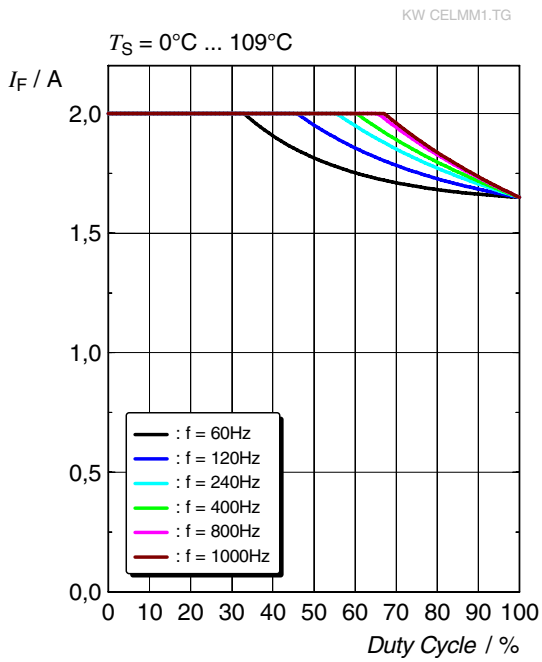
Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}$$



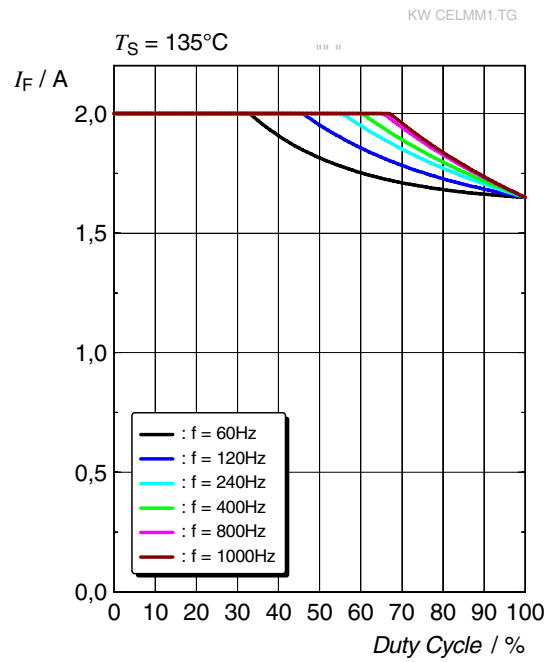
Permissible F. Handling Capability

f: Frequency

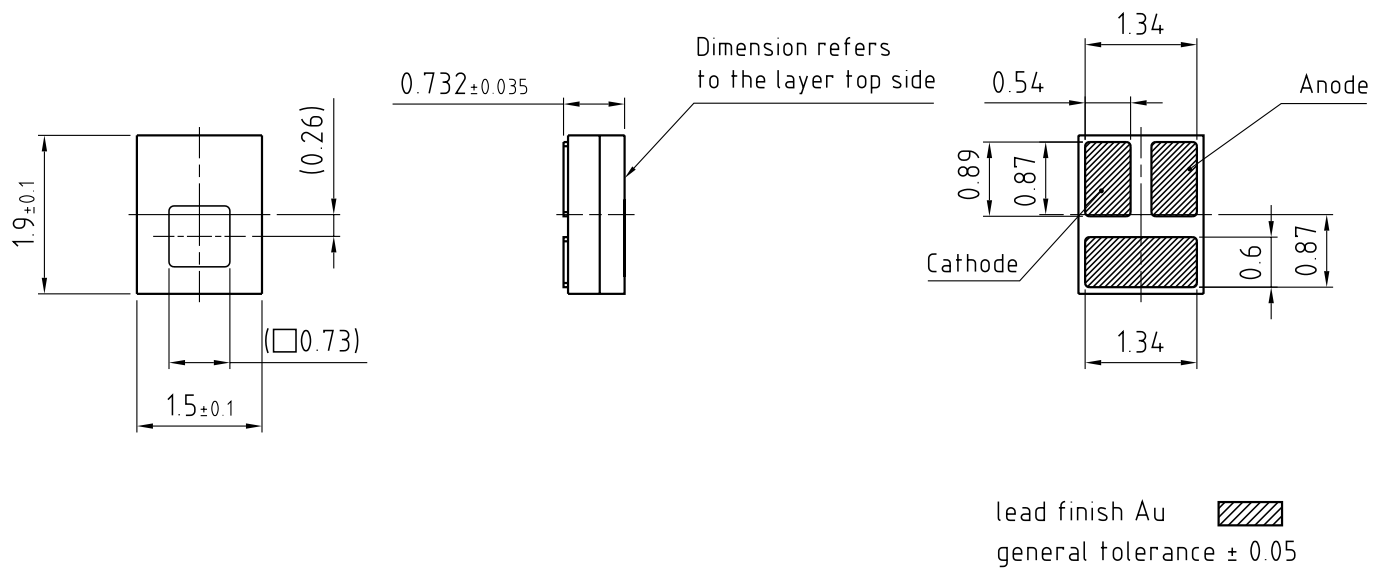


Permissible F. Handling Capability

f: Frequency



Dimensional Drawing ⁹⁾



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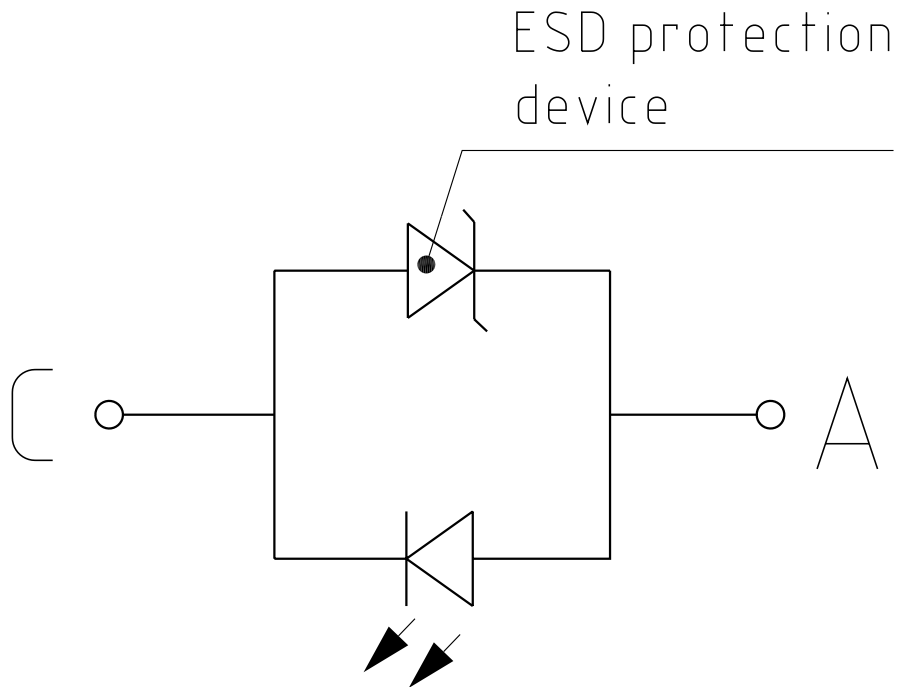
Further Information:

Approximate Weight: 7.8 mg

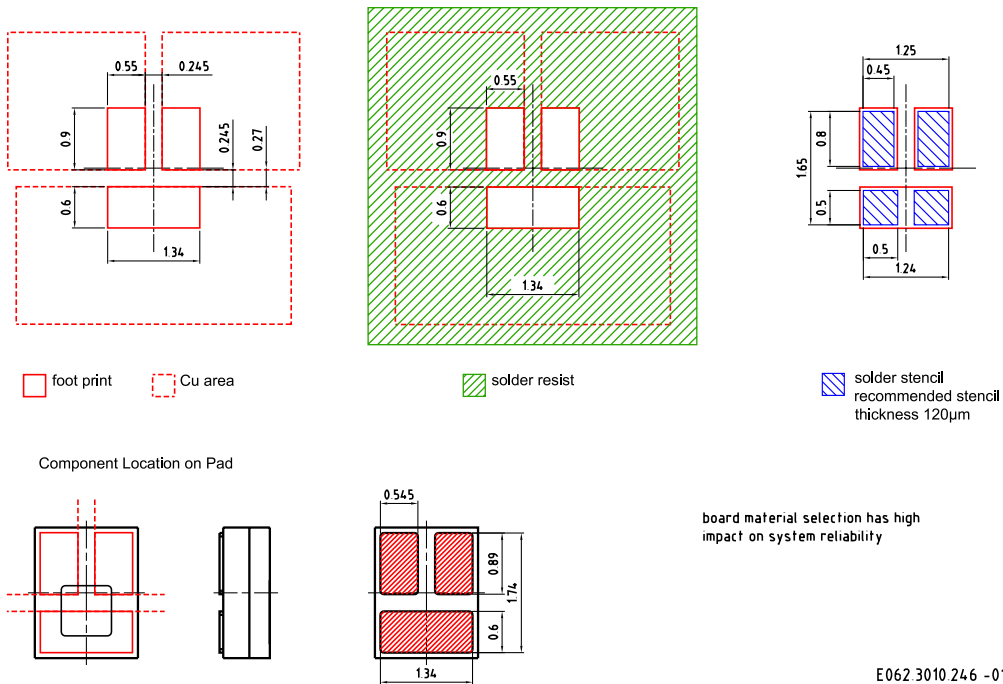
Corrosion test: Class: 3A
 Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC 60068-2-43)

ESD advice: The device is protected by ESD device which is connected in parallel to the Chip.

Electrical Internal Circuit



Recommended Solder Pad ⁹⁾



For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

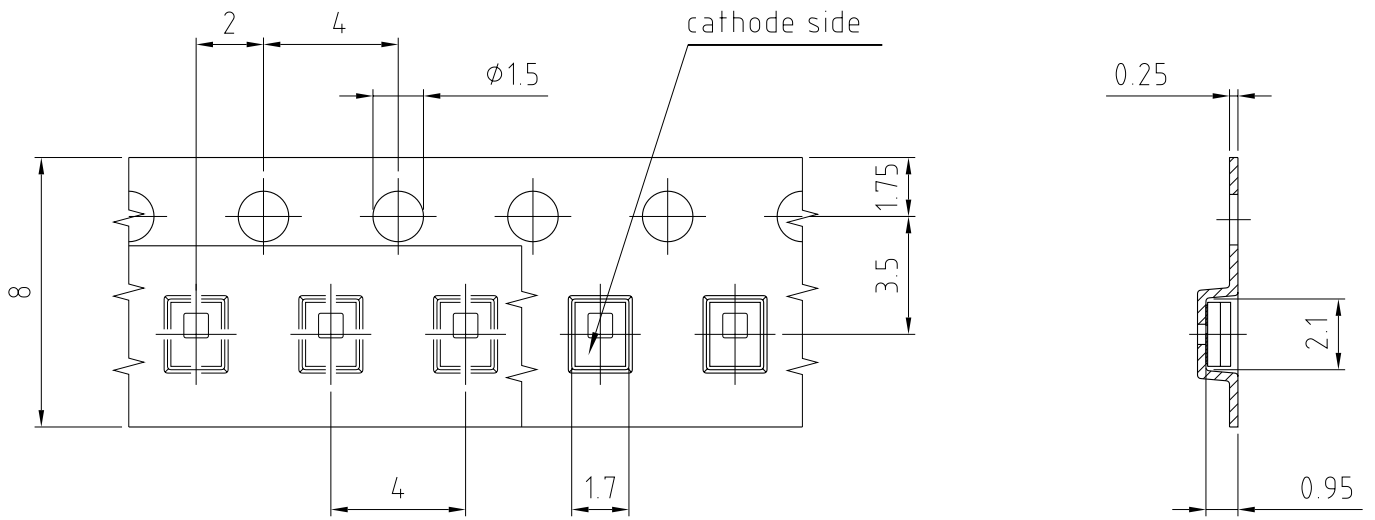


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak ^{*)} T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	260	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	6	K/s
Time 25 °C to T_p				480	s

All temperatures refer to the center of the package, measured on the top of the component

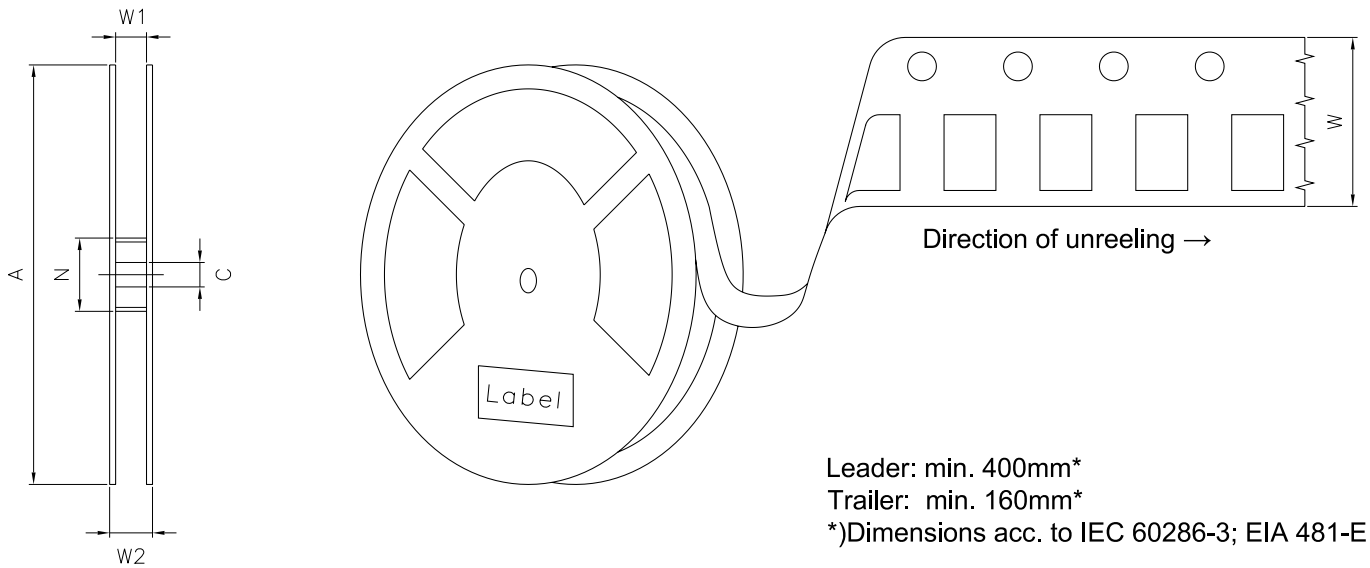
* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Taping ⁹⁾



C63062-A4372-B7-01

Tape and Reel ¹⁰⁾



Reel Dimensions

A	W	N _{min}	W ₁	W _{2max}	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	4000

Barcode-Product-Label (BPL)

OSRAM Opto Semiconductors LX XXXX BIN1: XX-XX-X-XXX-X


RoHS Compliant

(6P) BATCH NO: 1234567890 ML Temp ST
X XXX °C X

(1T) LOT NO: 1234567890 (9D) D/C: 1234

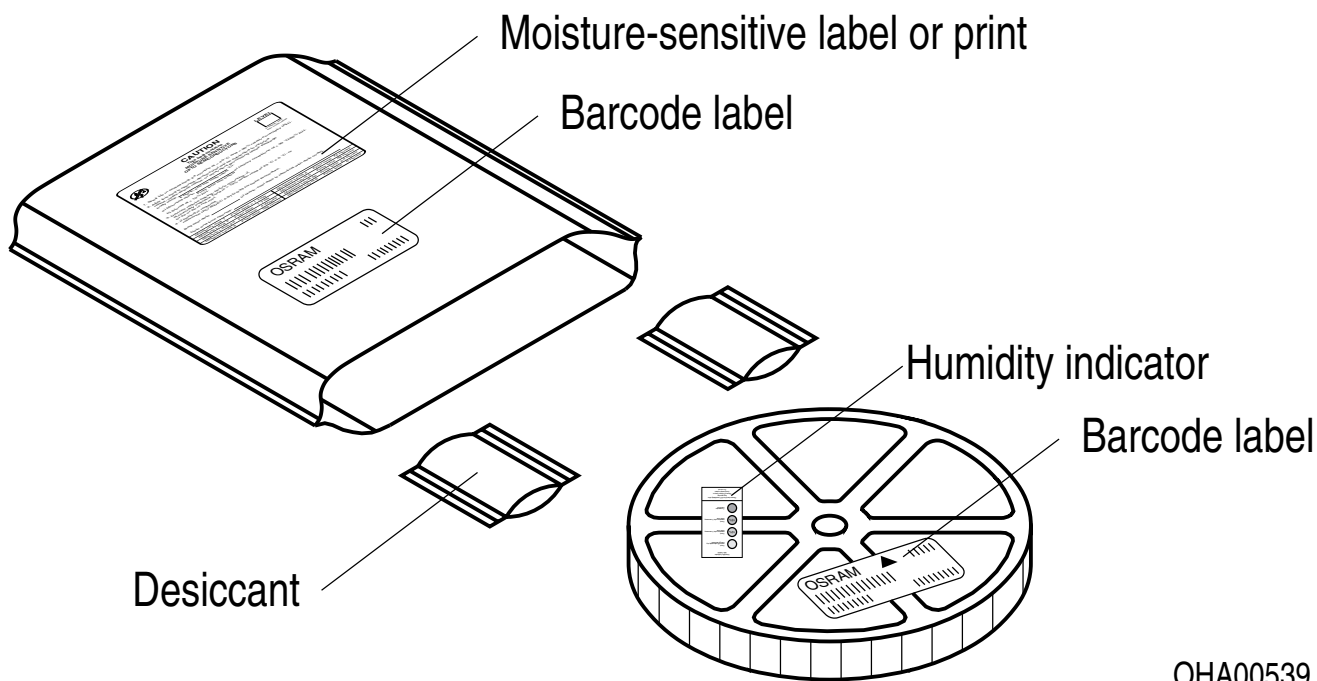
(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X

Pack: RXX
DEMY XXX
X_X123_1234.1234 X



OHA04563

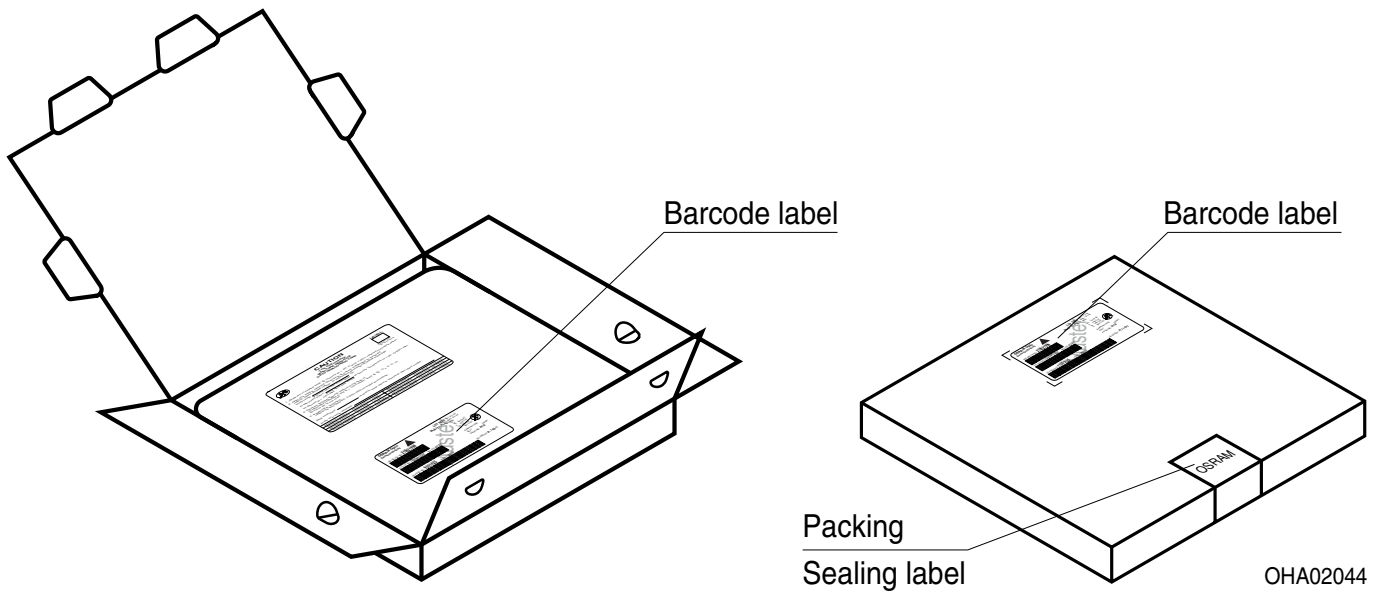
Dry Packing Process and Materials ⁹⁾



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Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

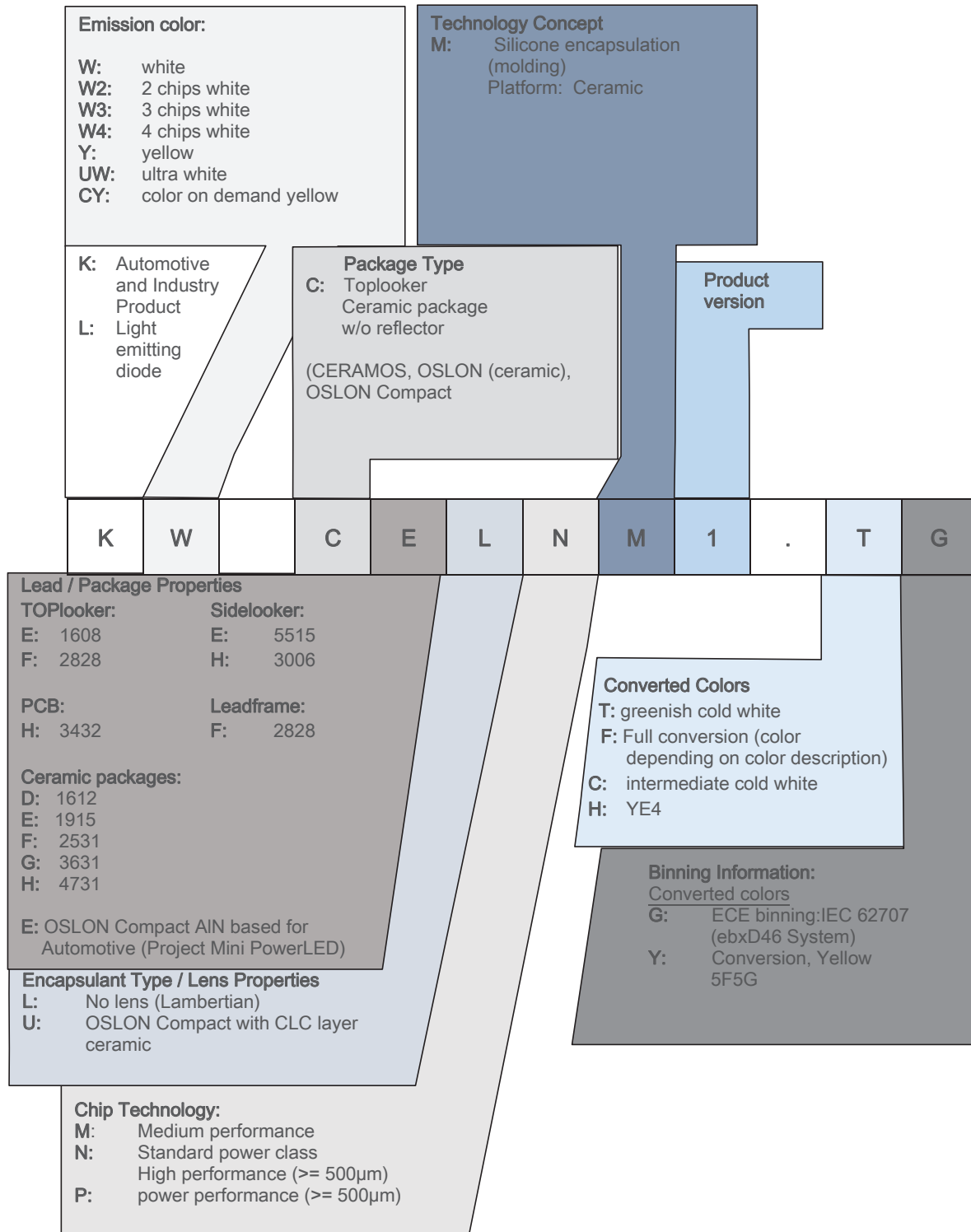
Schematic Transportation Box ⁹⁾



Dimensions of Transportation Box

Width	Length	Height
195 ± 5 mm	195 ± 5 mm	30 ± 5 mm

Type Designation System



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 1 ms, with an internal reproducibility of $\pm 8\%$ and an expanded uncertainty of $\pm 11\%$ (acc. to GUM with a coverage factor of $k = 3$).
- 2) **Operating Temperature:** The Operating Temperature Top is referenced to the Solderpoint Ts of this device. Proper current derating must be observed to maintain junction temperature below the maximum.
- 3) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 4) **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typically 1 ms, with an internal reproducibility of ± 0.005 and an expanded uncertainty of ± 0.01 (acc. to GUM with a coverage factor of $k = 3$).
- 5) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 1 ms, with an internal reproducibility of $\pm 0.05\text{ V}$ and an expanded uncertainty of $\pm 0.1\text{ V}$ (acc. to GUM with a coverage factor of $k = 3$).
- 6) **Thermal Resistance:** $R_{th\ max}$ is based on statistic values (6σ).
- 7) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 8) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 9) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 10) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.0	2019-12-05	Initial Version

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